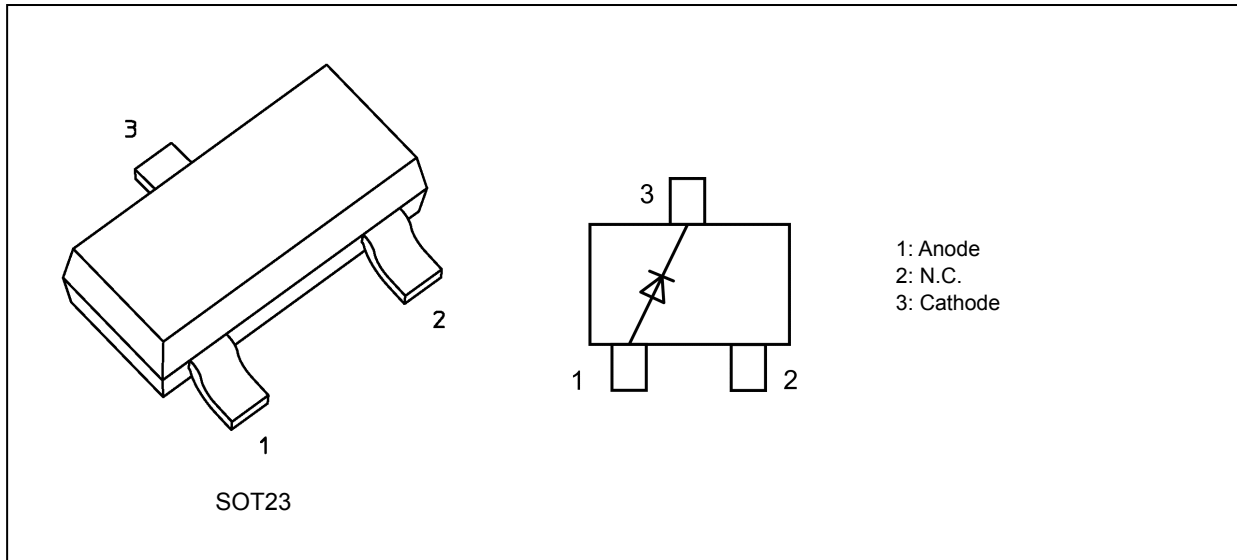


TBAS16

1. Applications

- Ultra-High-Speed Switching

2. Packaging and Internal Circuit



3. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Rating	Unit
Peak reverse voltage	V_{RM}		85	V
Reverse voltage	V_R		80	
Average rectified current	I_O		215	mA
Peak forward current	I_{FM}		500	
Non-repetitive peak forward surge current	I_{FSM}	(Note 1)	2	A
Power dissipation	P_D	(Note 2)	320	mW
Junction temperature	T_j		150	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width 10 ms

Note 2: Mounted on an FR4 board (25.4 mm × 25.4 mm × 1.6 mm, Cu pad: 0.42 mm² × 3)

Start of commercial production

2016-05

4. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Junction-to-ambient thermal resistance (Note 1)	$R_{th(j-a)}$	391	°C/W

Note 1: Mounted on an FR4 board (25.4 mm × 25.4 mm × 1.6 mm, Cu pad: 0.42 mm² × 3)

5. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage	V _F (1)	I _F = 1 mA	—	—	0.715	V
	V _F (2)	I _F = 10 mA	—	—	0.855	
	V _F (3)	I _F = 50 mA	—	—	1.0	
	V _F (4)	I _F = 150 mA	—	—	1.25	
Reverse current	I _R (1)	V _R = 25 V	—	—	30	nA
	I _R (2)	V _R = 80 V	—	—	500	
	I _R (3)	V _R = 25 V, T _j = 150 °C	—	—	30	μA
	I _R (4)	V _R = 80 V, T _j = 150 °C	—	—	100	
Total capacitance	C _t	V _R = 0 V, f = 1 MHz	—	0.9	—	pF
Reverse recovery time	t _{rr}	I _F = 10 mA, See Fig. 5.1	—	1.6	4.0	ns

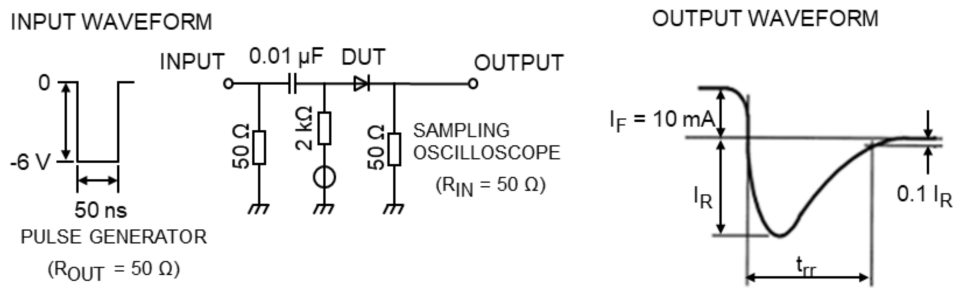


Fig. 5.1 Reverse recovery time (t_{rr}) Test circuit

6. Marking

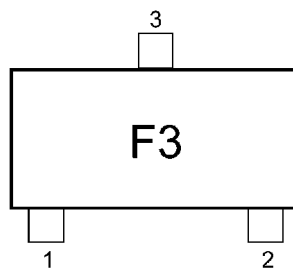


Fig. 6.1 Marking

7. Characteristics Curves (Note)

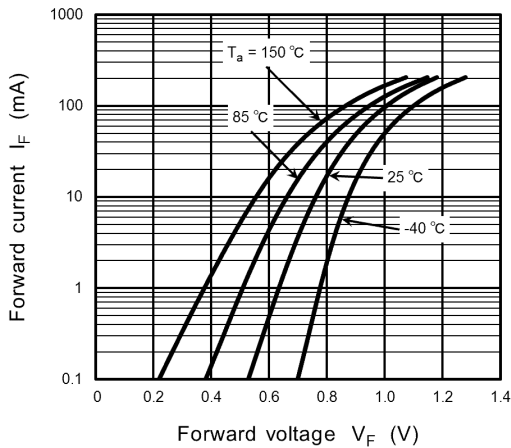


Fig. 7.1 $I_F - V_F$

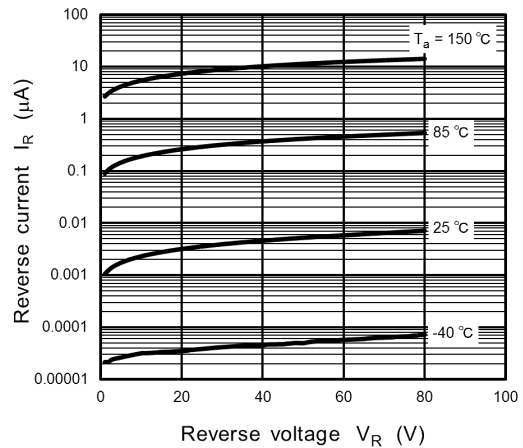


Fig. 7.2 $I_R - V_R$

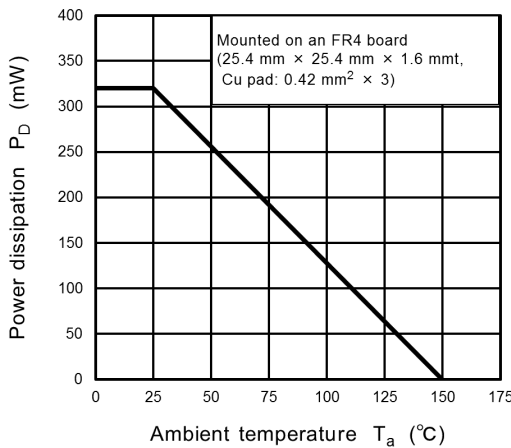
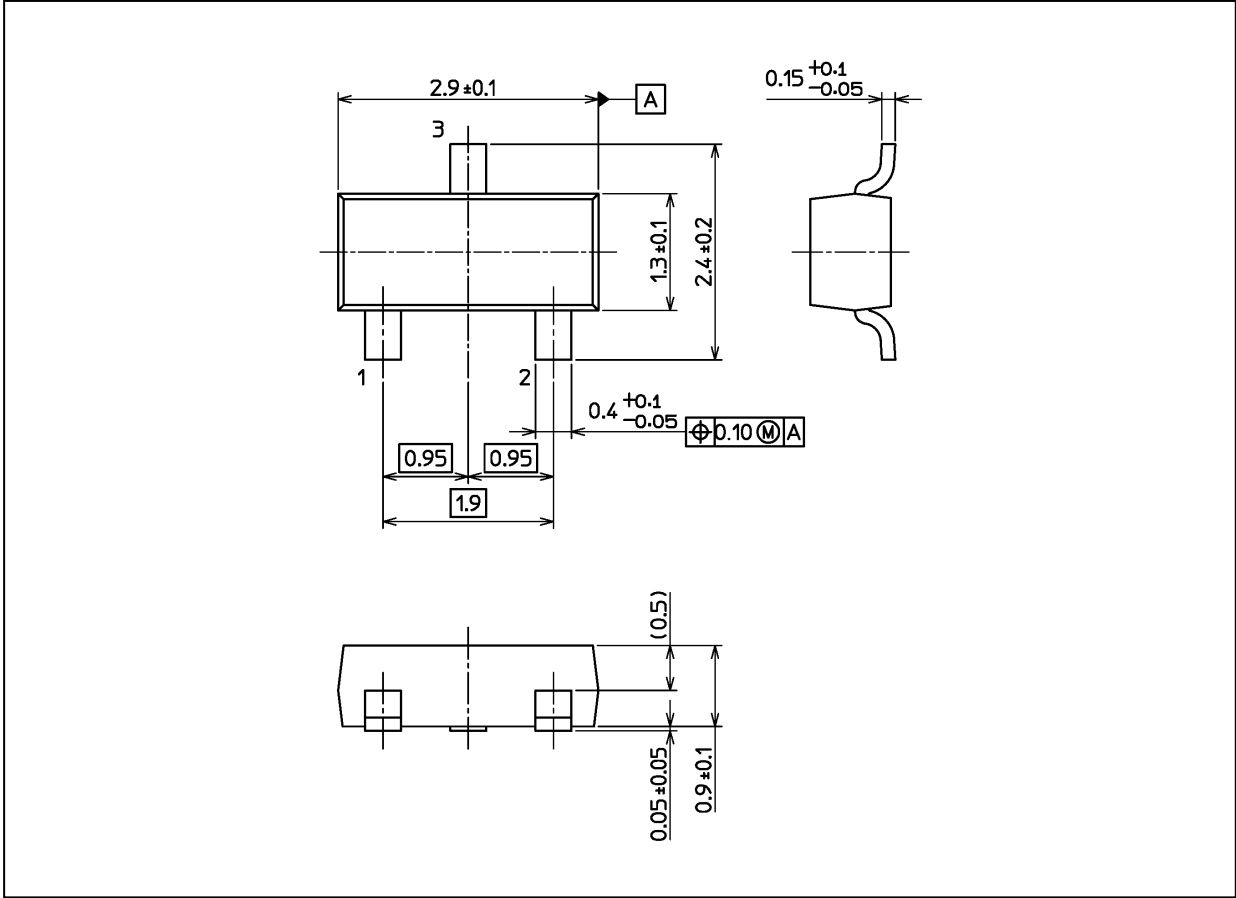


Fig. 7.3 $P_D - T_a$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 9 mg (typ.)

Package Name(s)
JEDEC: SOT-23
Nickname: SOT23

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